



## Product Change Notification / RMES-21CWWT073

### Date:

01-Oct-2021

### Product Category:

Ethernet Bridges, Ethernet PHYs

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4629 Final Notice: Qualification of STA as an additional assembly site for LAN7500x, LAN8820x and LAN9730x device families available in 56L VQFN (8x8x0.9mm) package.

### Affected CPNs:

[RMES-21CWWT073\\_Affected\\_CPN\\_10012021.pdf](#)  
[RMES-21CWWT073\\_Affected\\_CPN\\_10012021.csv](#)

### Notification Text:

**PCN Status:** Final notification.

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of STA as an additional assembly site for LAN7500x, LAN8820x and LAN9730x device families available in 56L VQFN (8x8x0.9mm) package.

### Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	STATS Chippac Ltd. (STA)
Wire material	PdCu	PdCu	CuPdAu

Die attach material	EN-4900F	EN-4900F	8290
Molding compound material	G631B	G631B	G700E
Lead frame material	C194	C194	C194
Lead frame DAP Surface Prep	Double Ring	Double Ring	Double Ring
Paddle size	240X240 mils	240X240 mils	236X236 mils

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying STA as an additional assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**October 31, 2021 (date code: 2145)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Due to unforeseen circumstances, that are out of Microchip's control, full qualification will be made available as soon as it is approved which may be after the estimated first ship date so that Microchip can maintain continuity of supply and not disrupt customer orders.

#### Time Table Summary:

Workweek	April 2021					->	October 2021					-->	December 2021			
	14	15	16	17	18		40	41	42	43	44		49	50	51	52
Initial PCN Issue Date				X												
Qual Report Availability							X									X
Final PCN Issue Date							X									
Estimated Implementation Date												X				

**Method to Identify Change:** Traceability code

**Estimated Qualification Completion Date:**December 2021

Note 1: This final PCN will be updated to include the Qualification report as soon as it is completed. Note 2: Please be advised the qualification completion times may be extended because of unforeseen business conditions.

**Revision History:** **April 22, 2021:** Issued initial notification. **October 01, 2021:** Issued final notification. Provided estimated first ship date to be on October 31, 2021. Updated the estimated qualification completion date from August 2021 to December 2021. Updated the lead frame DAP surface prep of STA assembly site from Ring plating to double ring plating in the pre and post change summary table. Attached the lead frame drawing pre and post change summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_RMES-21CWWT073\\_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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